



Form PTO-1449 (Substitute)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		Attorney Docket Number TEGL-01092US1		Serial/Patent Number 09/888,365	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> (Use several sheets if necessary)				Applicant/Patent Owner Stephen P. DeOrnellas, et al.			
				Filing/Issue Date June 22, 2001		Group Art Unit	
<b>U.S. PATENT DOCUMENTS</b>							
Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date
ARM		3,514,391	5/26/70	Hablanian et al.	204	298	
		4,033,287	7/5/77	Alexander, Jr., et al.	118	49.1	
		4,208,241	6/17/80	Harshbarger et al.	156	643	
		4,457,359	7/3/84	Holden	165	80	
		4,508,161	4/2/85	Holden	165	1	
		4,512,391	4/23/85	Harra	165	48	
		4,535,834	8/20/85	Turner	165	80	
		4,542,298	9/17/85	Holden	250	443	
		4,680,061	7/14/87	Lamont, Jr.	148	1.5	
		4,743,570	5/10/88	Lamont, Jr.	437	248	
		5,277,751	1/11/94	Ogle	156	643	
		5,362,350	11/8/94	Yanagida	156	643	
		5,445,709	8/29/95	Kojima et al.	216	71	
		5,708,557	1/13/98	Feigenbaum et al.	361	234	
		5,753,566	5/19/88	Hwang	438	715	
		5,800,619	9/1/98	Holland et al.	118	723	
		5,804,046	9/8/98	Sawada et al.	204	298.11	
		5,814,154	9/29/98	Boitnott	118	723	
		5,837,057	11/17/98	Koyama et al.	118	723	
		5,874,704	2/23/99	Gates	219	121.43	
<b>FOREIGN PATENT DOCUMENTS</b>							
Examiner Initial		Document Number	Date	Country	Class	Subclass	Trans- lation Yes   No
ARM		JP 07130712 A	5/19/95	Japan			X



OTHER DOCUMENTS (Include Author, Title, Date, Pertinent pages, etc.)	
	Ohno et al., <i>Reactive Ion Etching of Cooper Films in SiCl<sub>4</sub> and N<sub>2</sub> Mixture</i> , Japanese Journal of Applied Physics, Vol.28, No.6, June 1978, pp.11070-1072
	Krogh et al., <i>Spectroscopic Dianostics of Temperature-Controlled Trench Etching of Silicon</i> , Plasma Chemistry Plasma Processes, 10(2), 1990, pp.231-233, 239.
	PCT Notification of Transmittal of the International Search Report or the Declaration for PCT/US98/23297, Int'l Filing Date 03 November 1998, mailed 28 February 2000.
	Alan R. Reinberg, <i>Plasma Etch Equipment Technology, M. Triodes</i> , Perkin-Elmer Corporation, Norwalk, Connecticut, ©1989 by Academic Press, Inc., ISBN 0-12-469370-p; pp. 350-351
	Plasma Etching Technology, 10-11 February, 1997, Burlingame, California, Continuing Education in Engineering, University Extension, U. of California, Berkeley, <b>Plasma Etching Technology An Overview</b> , D.L. Flamm, 1992-1996, title 95011501v2, D.L. Flamm 1995, src5012608, 3 pgs
Examiner	Date Considered <u>03/07/02</u>
*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	
*1 = Copy not submitted because it was submitted in prior application SN <u>      </u> , filed <u>      </u> , 19 <u>      </u> .	
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		Filing/Issue Date <b>Herewith</b>	Group Art Unit <b>Unknown</b>

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Examiner Initial		Patent Number	Issue Date	Inventor	Class	Subclass	Filing Date
<i>DDMM</i>	1.	5,556,501	09/17/96	Collins et al.	156	345	04/01/93
	2.	5,628,869	05/13/97	Mallon	438	694	05/09/94
	3.	5,800,618	09/01/98	Niori et al.	118	723	06/30/94
	4.	5,820,947	10/13/98	Itoh	427	577	03/19/97
	5.	5,876,504	03/02/99	Fuji et al.	118	723	09/17/97
	6.	5,904,487	05/18/99	Conboy et al.	438	14	10/08/96
	7.	6,071,573	06/06/00	Koemtzopoulos et al.	427	578	12/30/97

Examiner <i>Delepradio</i>		Date Considered <i>03/07/02</i>
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<p>*1 = Copy not submitted because it was submitted in prior application SN <u>  </u> / <u>  </u> , filed <u>  </u> , 20<u>  </u> , relied on under 35 USC §120.</p>		
<p>*2 = Copy not submitted because it was submitted in prior application SN <u>  </u> / <u>  </u> , filed <u>  </u> , 20<u>  </u> , relied on under 35 USC §120.</p>		